

REV	DATE	ECN NO.	MODIFICATION	APPROVER
A	2016/10/14		NEW	Jason_Lee
A1	2017/05/15	RD00317051501	SIZE CHANGE	Jason_Lee

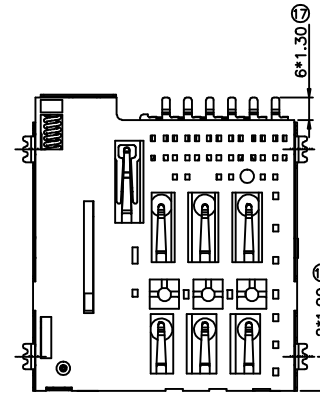
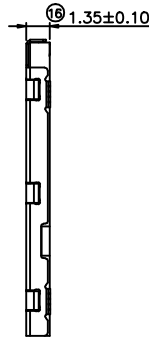
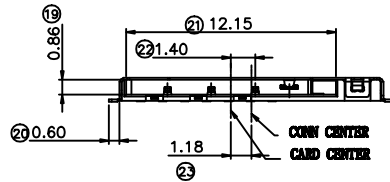
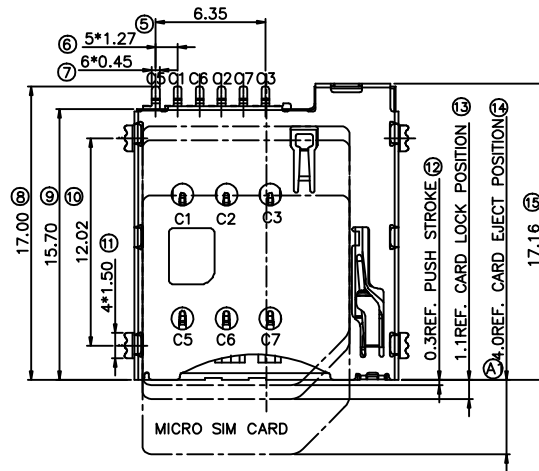
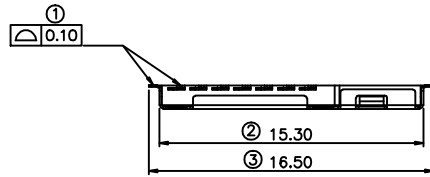
NOTES:

MATERIAL:

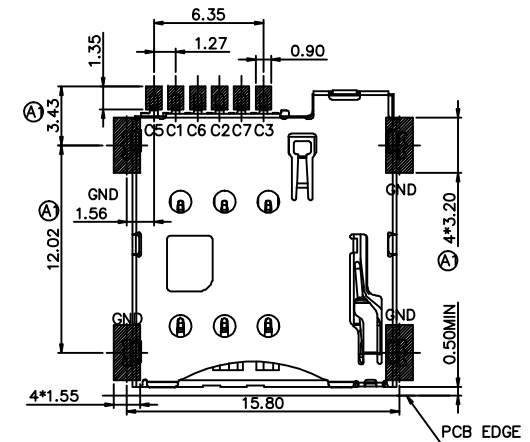
Housing: High Temperature thermoplastic, UL94V-0
Terminal: Copper Alloy
Shell: Stainless

SPECIALITY:

Rated Current: 0.5A MAX
Rated Voltage: 50V
Ambient Temperature Range: -40°C~+85°C
Ambient Humidity Range: ≤95% R.H. Max.
Contact Resistance: 100mΩ Max
Insulation Resistance: 1000MΩ/250V DC
Dielectric Withstanding Voltage: 500V AC
Durability: 5000 cycles
Temperature 260±5°C

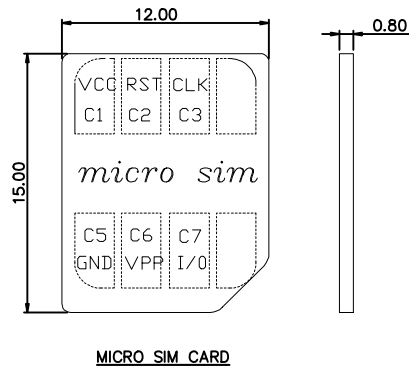


IM pin Assignment	
IN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



■ SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE±0.05



GENERAL TOLERANCE		UNITS	NAME: MICRO SIM CARD 6P PUSH PUSH		ATOM [®] 深圳市爱特姆科技有限公司 SHENZHEN ATOM TECHNOLOGY CO., LTD.	
SELECT	TOL.	1	2	3	PART NO:	TITLE: CUSTOMER DRAWING FOR MICRO SIM CARD 6P P-P H=1.35mm 不带检测脚 无柱
X.XXX	±0.10±0.05±0.15				SI63C-01200	
X.XX	±0.15±0.13±0.25				APPD:	DWG NO. ATOM-A03338
X.X	±0.20±0.25±0.5				CHKD:	
X.	±0.30±0.38±1.00				DR: JACK	
ANGLE	±2°					